

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) An exposure apparatus which exposes a substrate by radiating an exposure light beam onto the substrate through a liquid, the exposure apparatus comprising:

a substrate stage which has a substrate-holding member for holding the substrate and which is ~~movable while holding the substrate by the aid of the substrate-holding member;~~
movable; and

a temperature adjustment system which performs temperature adjustment for the substrate-holding ~~member~~member depending on a temperature of the liquid to be supplied onto the substrate held by the substrate-holding member.

2. (Original) The exposure apparatus according to claim 1, wherein the temperature adjustment system performs the temperature adjustment for the substrate-holding member so that heat transfer is reduced between the substrate and the liquid on the substrate.

3. (Original) The exposure apparatus according to claim 1, wherein the temperature adjustment system performs the temperature adjustment for the substrate-holding member so that no temperature change of the liquid is caused by contact between the liquid and the substrate.

4. (Original) The exposure apparatus according to claim 3, wherein the temperature adjustment system performs the temperature adjustment for the substrate-holding member so that no temperature distribution is generated in the liquid.

5. (Original) The exposure apparatus according to claim 3, further comprising a surface position-detecting unit which detects surface position information about a surface of the substrate by emitting a detecting light beam onto the substrate through the liquid and

receiving a reflected light beam from the substrate through the liquid, wherein the temperature adjustment system performs the temperature adjustment for the substrate-holding member to suppress measurement error of the surface position-detecting unit due to the temperature change of the liquid.

6. (Original) The exposure apparatus according to claim 1, wherein the temperature adjustment system performs the temperature adjustment for the substrate-holding member so that no temperature change of the substrate is caused by contact between the liquid and the substrate.

7. (Currently Amended) The exposure apparatus according to claim 6, further comprising a mark-detecting system which detects an alignment mark on the substrate not through the liquid, wherein the temperature adjustment system performs the temperature adjustment for the substrate-holding member so that a temperature no temperature change of the substrate is not changed caused by the contact between the liquid and the substrate after detecting the mark by the mark-detecting system.

8. (Original) The exposure apparatus according to claim 1, wherein the temperature adjustment system uses a liquid which is same as the liquid to be supplied onto the substrate to perform the temperature adjustment for the substrate-holding member.

9. (Canceled)

10. (Original) The exposure apparatus according to claim 1, further comprising a temperature sensor which measures a temperature of the substrate-holding member.

11-29. (Canceled)

30. (Currently Amended) An exposure apparatus which exposes a substrate by radiating an exposure light beam onto the substrate through a liquid, the exposure apparatus comprising:

a first substrate stage which has a substrate-holding member for holding the substrate and which is ~~movable while holding the substrate by the aid of the substrate holding member; movable;~~

a second substrate stage which has a substrate-holding member for holding the substrate and which is ~~movable while holding the substrate by the aid of the substrate holding member; movable;~~

a measuring station which performs measurement for the substrate held by one of the stages;

an exposure station which performs exposure for the substrate held by the other of the stages; ~~stages, the exposure station being provided with a liquid supply system which supplies the liquid onto the substrate; and~~

temperature adjustment systems which are provided for the first substrate stage and the second substrate stage respectively and which perform temperature adjustment for the substrate-holding member of each of the stages ~~in the measuring station depending on a temperature of the liquid to be supplied from the liquid supply system.~~

31. (Original) The exposure apparatus according to claim 30, wherein the measurement for the substrate in the measuring station includes measurement of surface position information about a surface of the substrate.

32. (Original) The exposure apparatus according to claim 30, wherein the measurement for the substrate in the measuring station includes detection of an alignment mark on the substrate.

33. (Original) The exposure apparatus according to claim 30, wherein the temperature adjustment system performs the temperature adjustment for the substrate-holding member before performing the measurement for the substrate.

34. (Canceled)

35. (Currently Amended) The exposure apparatus according to claim 30, wherein the temperature adjustment system performs, after the measurement for the substrate in the measuring station, the temperature adjustment for the substrate-holding member to suppress temperature change of the ~~substrate caused by contact with the liquid supplied onto the substrate in the exposure station.~~ substrate.

36-43. (Canceled)

44. (Currently Amended) A method for producing a device, ~~comprising~~ comprising:

exposing a substrate using the exposure apparatus as defined in ~~claim 1-claim 1; and~~ processing the exposed substrate.

45-64. (Canceled)

65. (Previously Presented) The exposure apparatus according to claim 30, further comprising a projection optical system which projects an image of a pattern onto the substrate through the liquid.

66-67. (Canceled)

68. (Currently Amended) A method for producing a device, comprising: ~~comprising exposing a substrate~~ using the exposure apparatus as defined in ~~claim 30.~~ claim 30; and

processing the exposed substrate.

69. (Canceled)

70. (New) The exposure apparatus according to claim 1, wherein the temperature adjustment system performs the temperature adjustment for the substrate-holding member so that the temperature of the substrate-holding member is the same as the temperature of the liquid to be supplied onto the substrate held by the substrate-holding member.

71. (New) The exposure apparatus according to claim 1, wherein the temperature adjustment system performs the temperature adjustment for the substrate-holding member so that no deformation of the substrate is caused by contact between the liquid and the substrate.

72. (New) The exposure apparatus according to claim 10, wherein the temperature adjustment system performs the temperature adjust for the substrate-holding member so that the measured temperature of the substrate-holding member is the same as the temperature of the liquid to be supplied onto the substrate held by the substrate-holding member.

73. (New) The exposure apparatus according to claim 1, further comprising a liquid supply system having a supply inlet, the liquid supplied onto the substrate from the supply inlet covering only a portion of a surface of the substrate.

74. (New) An exposure method comprising:

holding a substrate by a substrate-holding member;
supplying a liquid onto the substrate held by the substrate-holding member so that the supplied liquid covers only a portion of a surface of the substrate held by the substrate-holding member;

controlling a temperature of the substrate-holding member depending on a temperature of the liquid to be supplied onto the substrate held by the substrate-holding member; and

exposing the substrate by radiating an exposure light beam onto the substrate through the supplied liquid.

75. (New) The exposure method according to claim 74, wherein the temperature of the substrate-holding member is controlled so that heat transfer between the substrate and the supplied liquid is prevented.

76. (New) The exposure method according to claim 74, wherein the temperature of the substrate-holding member is controlled so that temperature change of the liquid on the substrate is prevented.

77. (New) The exposure method according to claim 74, wherein the temperature of the substrate-holding member is controlled so that temperature change of the substrate due to contact between the supplied liquid and the substrate is prevented.

78. (New) The exposure method according to claim 77, further comprising detecting an alignment mark on the substrate held by the substrate-holding member not through the liquid, wherein the temperature of the substrate-holding member is controlled so that the temperature change of the substrate caused after detecting the mark is prevented.

79. (New) The exposure method according to claim 74, wherein the temperature of the substrate-holding member is controlled using a liquid which is same as the liquid to be supplied onto the substrate.

80. (New) The exposure method according to claim 79, wherein the temperature of the substrate-holding member is controlled by flowing the liquid in the substrate-holding member.

81. (New) The exposure method according to claim 74, further comprising measuring the temperature of the substrate-holding member, wherein the temperature of the substrate-holding member is controlled so that the measured temperature of the substrate-holding member is the same as the temperature of the liquid to be supplied onto the substrate held by the substrate-holding member.

82. (New) The exposure method according to claim 74, wherein the temperature of the substrate-holding member is controlled so that the temperature of the substrate-holding member is the same as the temperature of the liquid to be supplied onto the substrate held by the substrate-holding member.

83. (New) The exposure method according to claim 74, wherein the temperature of the substrate-holding member is controlled so that deformation of the substrate due to contact between the supplied liquid and the substrate is prevented.